





DUAL SURFACE MOUNT SWITCHING DIODE

Features

- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automated Insertion
- For General Purpose Switching Applications
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Notes 3 & 4)
- Qualified to AEC-Q101 Standards for High Reliability

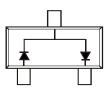
Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208 (3)
- Polarity: See Diagram
- Weight: 0.008 grams (approximate)

SOT23



Top View



Top View Internal Schematic

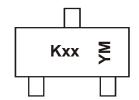
Ordering Information (Note 5)

Part Number	Compliance	Case	Packaging
BAV99-7-F	Standard	SOT23	3,000/Tape & Reel
BAV99-13-F	Standard	SOT23	10,000/Tape & Reel
BAV99Q-7-F	Automotive	SOT23	3,000/Tape & Reel
BAV99Q-13-F	Automotive	SOT23	10,000/Tape & Reel

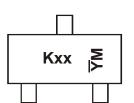
Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Product manufactured with Date Code 9W (week 39, 2009) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 9W are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ Fire Retardants.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



xx = JE, Product Type Marking Code YM = Date Code Marking for Shanghai Assembly / Test site Y = Year (ex: A = 2013) M = Month (ex: 9 = September)



xx = JE, Product Type Marking Code

YM = Date Code Marking for Chengdu
Assembly / Test site

 \overline{Y} = Year (ex: A = 2013) M = Month (ex: 9 = September)

Date Code Key

Year	1998	1999		2006	2007	2008	2009	2010	2011	2012	2013	2014	2015	2016	2017
Code	J	K		Т	U	V	W	Χ	Υ	Z	Α	В	С	D	Е
Month	Jan	Fe	b	Mar	Apr	May	Ju	n	Jul	Aug	Sep	Oc	t I	Nov	Dec
Code	1	2		3	4	5	6		7	8	9	0		N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage		V_{RM}	100	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V _{RRM} V _{RWM} V _R	75	V
RMS Reverse Voltage		V _{R(RMS)}	53	V
Forward Continuous Current (Note 6)		I _{FM}	300	mA
Non-Repetitive Peak Forward Surge Current	@ t = 1.0µs @ t = 1.0s	I _{FSM}	2.0 1.0	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P_{D}	350	mW
Thermal Resistance Junction to Ambient Air (Note 6)	$R_{ heta JA}$	357	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

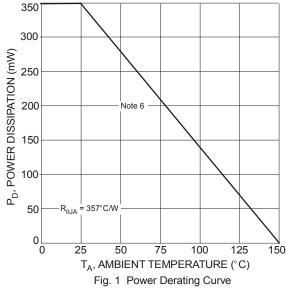
Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V _{(BR)R}	75	_	V	I _R = 2.5μA
Forward Voltage	V _F	_	0.715 0.855 1.0 1.25	V	I _F = 1.0mA I _F = 10mA I _F = 50mA I _F = 150mA
Reverse Current (Note 7)	I _R	_	2.5 50 30 25	μΑ μΑ μΑ nA	$V_R = 75V$ $V_R = 75V$, $T_J = +150$ °C $V_R = 25V$, $T_J = +150$ °C $V_R = 20V$
Total Capacitance	C _T	_	2.0	pF	V _R = 0, f = 1.0MHz
Reverse Recovery Time	t _{rr}	_	4.0	ns	$I_F = I_R = 10 \text{mA},$ $I_{rr} = 0.1 \text{ x } I_R, R_L = 100 \Omega$

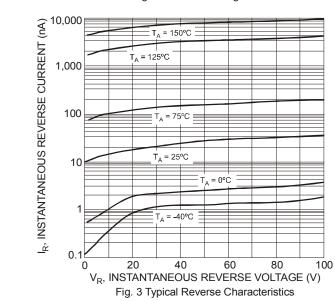
Notes:

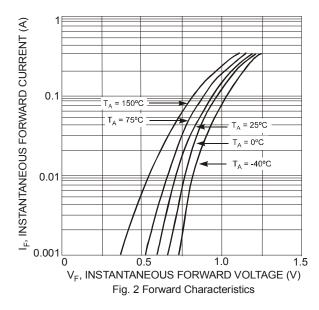
^{6.} Part mounted on Polymide PC board with pad dimensions 1.13mm x 1.27mm.

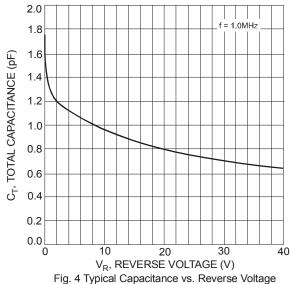
^{7.} Short duration pulse test used to minimize self-heating effect.





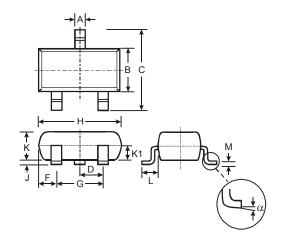






Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

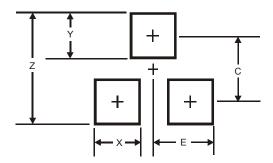


SOT23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
C	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
Н	2.80	3.00	2.90				
7	0.013	0.10	0.05				
K	0.903	1.10	1.00				
K1	-	-	0.400				
L	0.45	0.61	0.55				
М	0.085	0.18	0.11				
α	0°	8°	-				
All Dimensions in mm							



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.9
Х	0.8
Υ	0.9
С	2.0
E	1.35

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